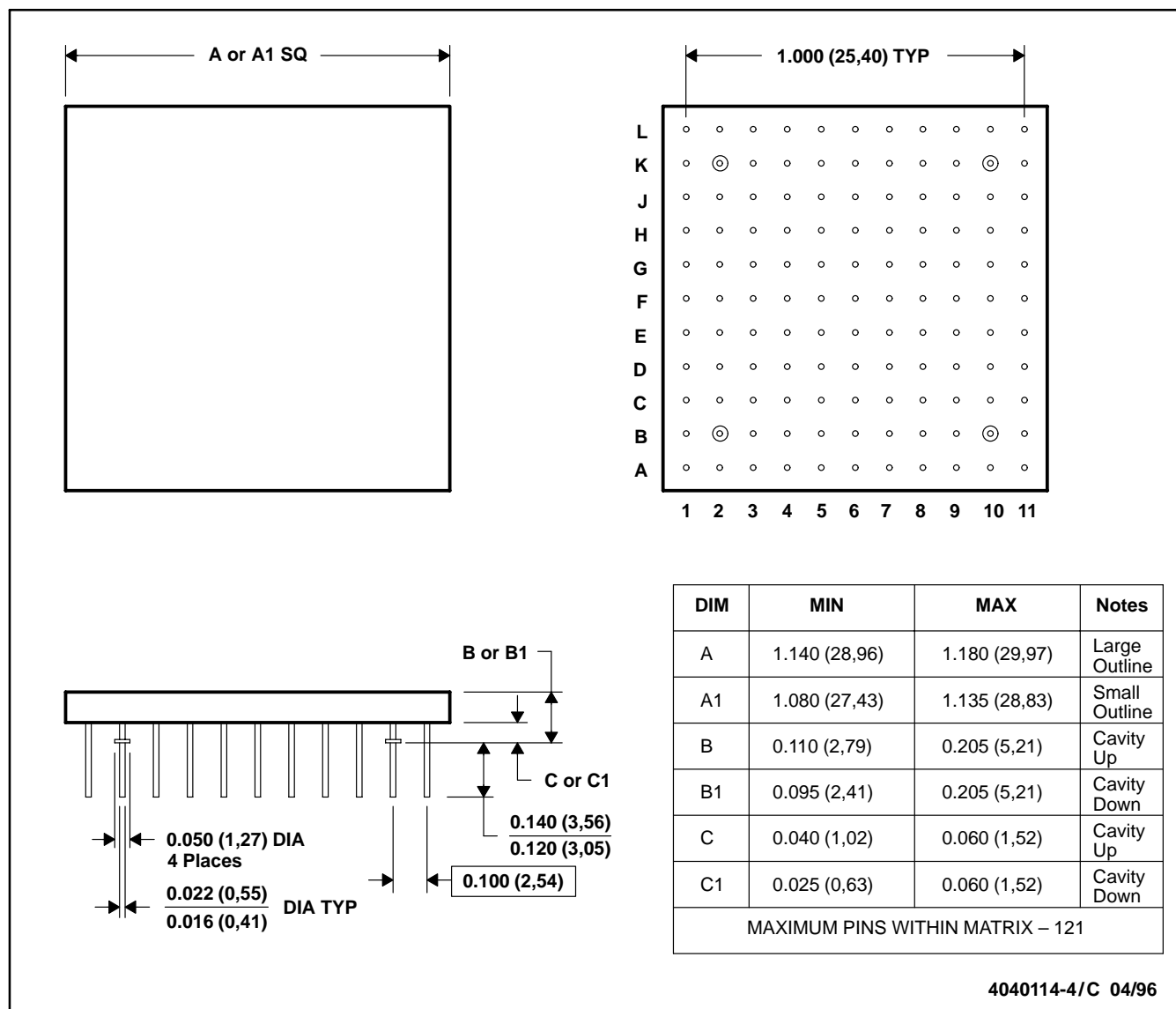


GA-GB (S-CPGA-P11 X 11)

CERAMIC PIN GRID ARRAY PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Index mark may appear on top or bottom depending on package vendor.
 - Pins are located within 0.010 (0,25) diameter of true position relative to each other at maximum material condition and within 0.030 (0,76) diameter relative to the edge of the ceramic.
 - This package can be hermetically sealed with metal lids or with ceramic lids using glass frit.
 - The pins can be gold plated or solder dipped.
 - Falls within MIL-STD-1835 CMGA3-PN and CMGA15-PN and JEDEC MO-067AC and MO-066AC, respectively

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